

MPS 3H 132 S

Grinding
machines

High Precision even in Large Scale Production

Genauigkeits
Maschinenbau
Nürnberg GmbH



Characteristics

Precision surface grinding machine with fully automatic grinding cycles, inprocess gage, vacuum clamping and controllable damage depths.

Application areas

In high production, when grinding all semiconductor materials, quartz, glass, ceramic and other brittle materials.

Optimum use

Back grinding of silicon wafers up to 200 mm diameter.
Grinding of orientation flats on ingots up to 200 mm diameter and 650 mm in length. The machine can also be supplied in a special design for ingots up to 1,000 mm in length.

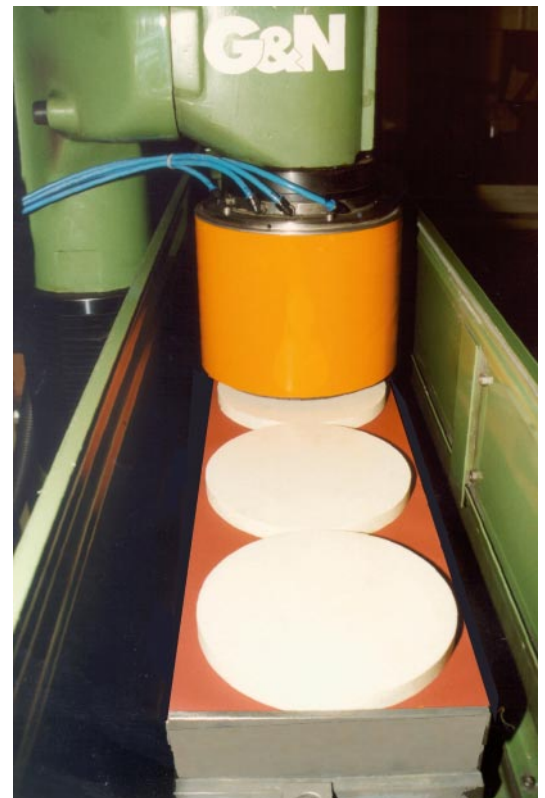


Accessories

Comprehensive accessories optimize machine use over a broad range of materials and workpieces.

Technical Data

Wafer-ø:	2"	3"	100mm	125mm	150mm	200mm
Table load:	30	16	9	5	4	2 Wafer
throughput/h:	150	87	58	30	24	12 Wafer
Exemplary assumption:	removal 100 µm, surface finish CLA approx. 0.25 µm, damage depth approx. 8 µm					
Table speed (infinitely variable)	0 - 10 rpm					
Electrical connection	10 kW					
Compressed air	4 - 5 bar					
Space	approx. 10 m ²					
Net weight	approx. 1100 kg					



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